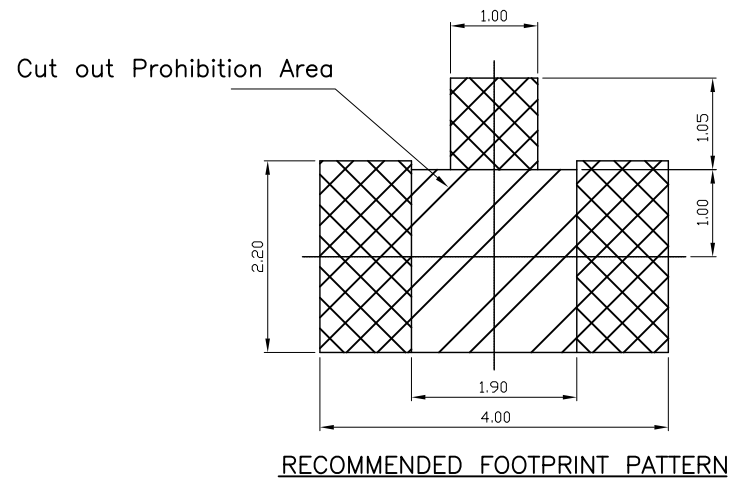
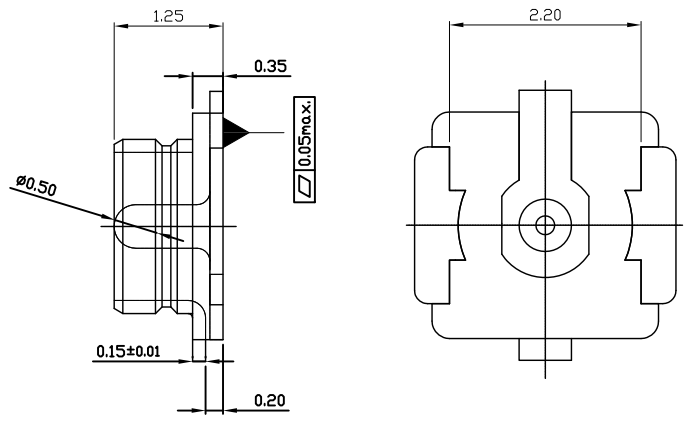
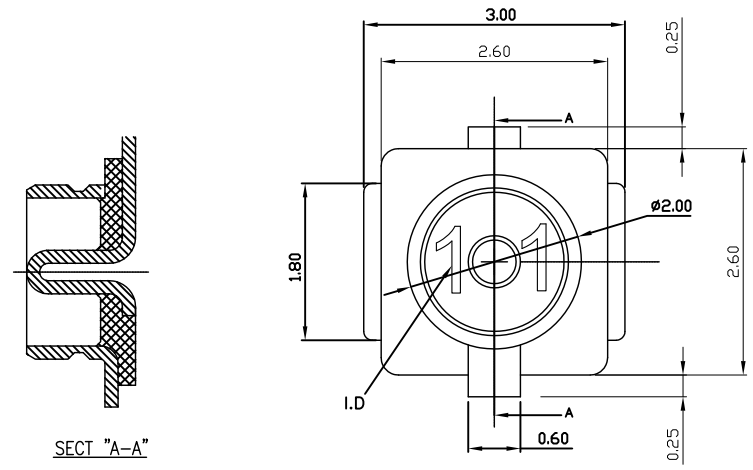


REV.	DESCRIPTION	DATE	DWN	APVD
1	PRELIMINARY	24MAR09	JC	BC

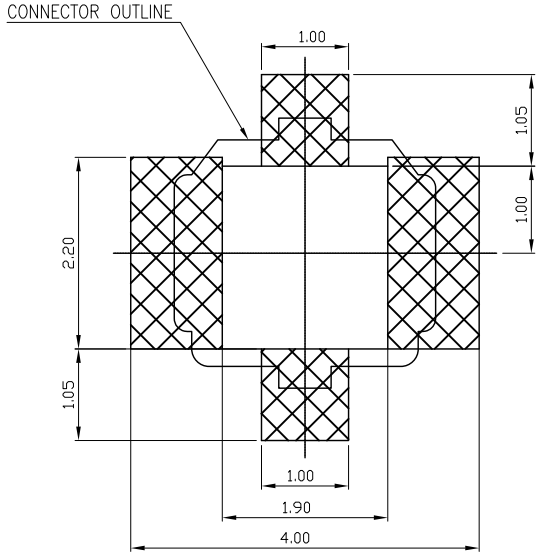
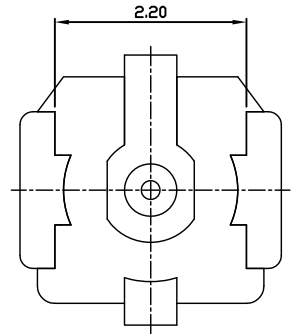
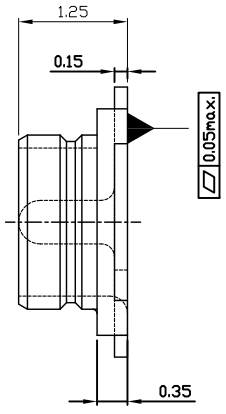
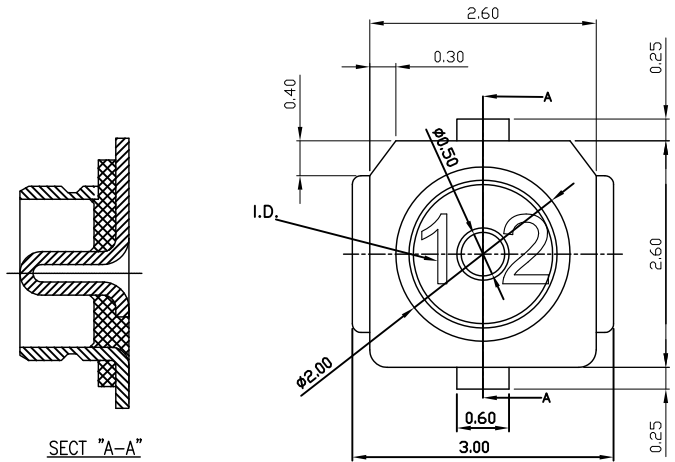


- Material
 - Contact: Copper alloy, Brass per JIS C2680 or other equivalent copper alloy.
 - Ground contact: Copper alloy, Ph. Bronze per JIS C5191 or other equivalent.
 - Housing: LCP resin with 30% G.F. filled, UL94v-0.
 - Finish:
 - Contact : Gold 0.1 μm (4 u") mini over 1.27 μm (50 u") Nickel under plating.
 - Ground contact: Gold flash over 1.27 μm (50 u") Nickel under plating.
- 毛邊 : 0.05MAX

SMXLH67113
PART NUMBER

TOLERANCES UNLESS OTHERWISE SPECIFIED:		DWN	24MAR2009	HAOGUO XING YE SHARE CO.,LTD.	
0 PLC	$\pm -$	CHK	24MAR2009		
1 PLC	± 0.2	APVD	24MAR2009		
2 PLC	± 0.1	NAME	BEST_CHANG		
3 PLC	± 0.05	PRODUCT SPEC		MHF Micro Coaxial RF receptacle 3P	
4 PLC	$\pm -$	APPLICATION SPEC		SIZE	DRAWING NO
ANGLES	$\pm 3'$	WEIGHT	- GRAMS	A3	-
MATERIAL	SEE NOTE	PROJECTION		DIMENSIONS:	MM
FINISH	SEE NOTE	CUSTOMER DRAWING	SCALE	SHEET	1 OF 1
RESTRICTED TO		REV	1		

REV.	DESCRIPTION	DATE	DWN	APVD
1	PRELIMINARY	24MAR09	JC	BC



RECOMMENDED FOOTPRINT PATTERN

1. Material

- Contact: Copper alloy, Brass per JIS C2680 or other equivalent copper alloy.
- Ground Contact: Copper alloy, Ph. Bronze per JIS C5191 or other equivalent.
- Housing: LCP resin with 30% G.F. filled, UL94v-0.
- Finish:
- Contact : Gold 0.1 um (4 u") mini over 1.27 um (50 u") Nickel under plating.
- Ground contact: Gold flash over 1.27 um (50 u") Nickel under plating.

2. 毛邊 : 0.05MAX

SMXLH67114
PART NUMBER

TOLERANCES UNLESS OTHERWISE SPECIFIED:		DWN 24MAR2009		HAOGUO XING YE SHARE CO.,LTD.	
0 PLC	± -	CHK	24MAR2009		
1 PLC	± 0.2	MARKS_CHEN		NAME	
2 PLC	± 0.1	APVD 24MAR2009			
3 PLC	± 0.05	BEST_CHANG		MHF Micro Coaxial RF receptacle 4P	
4 PLC	± -	PRODUCT SPEC			
ANGLES	± 3°	APPLICATION SPEC		SIZE DRAWING NO RESTRICTED TO	
MATERIAL SEE NOTE		WEIGHT - GRAMS			
FINISH SEE NOTE		DIMENSIONS: MM		CUSTOMER DRAWING SCALE - SHEET 1 of 1 REV 1	
PROJECTION		FIRST ANGLE			